

24 November 2021

Notification for Recruitment of Junior Research Fellow– Electrical Engineering
Project funded by SERB Start-up Research Grant
Ref: IITPKD/2021/031/EE/SRV

- **Project areas:** Design and development of efficient interfacing circuit for moisture sensing. Work will involve electronic circuit design, sensor design and development, PCB layout, and microcontroller programming.
- **Required skills:** Good competence in analog circuit design and simulation, PCB layout, microcontroller programming. Preference will be given for candidates who have demonstrated successful sensor design/analog circuit design/measurements and instrumentation.
- **Eligibility:** B.E./B.Tech or M.E./M.Tech from reputed institutions with specialization in areas allied to the advertised project areas.
- **Age:** Candidates who are below 31 years of age, as on the closing date of application, with relaxation to candidates belonging to OBC/SC/ST/PWD categories and women applicants as per Government of India norms.
- **Appointment duration:** Initially for six months and extendable depending on satisfactory performance of the candidate and availability of funds.
- **No. of Positions:** One
- **Salary Particulars:** The monthly remuneration for this position will be Rs. 31,000/- (Thirty One Thousand Rupees Only). Hostel accommodation may be provided at the institute based on availability on a chargeable basis. In case of non-availability of institute hostel, admissible HRA will be provided as per Government of India rules.
- **Deadline for application:** 05 December 2021 (Sunday)

Candidates satisfying the required skills may send their resumes and certificates pertaining to educational qualifications starting from class X (in a single PDF) to “sreenath@iitpkd.ac.in”. The subject of the application e-mail should be **Application for Junior Research Fellow - IITPKD/2021/031/EE/SRV**. Also, candidates must fill up the following Google Form <https://forms.gle/MaiST6QRdT9EDPF98>. The candidate is expected to join immediately after receiving the offer letter.
